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FDS6898A

Dual N-Channel Logic Level PWM Optimized PowerTrench® MOSFET

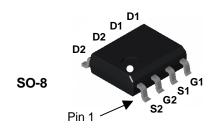
General Description

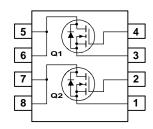
These N-Channel Logic Level MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Features

- 9.4 A, 20 V $R_{DS(ON)} = 14~m\Omega~@~V_{GS} = 4.5~V$ $R_{DS(ON)} = 18~m\Omega~@~V_{GS} = 2.5~V$
- Low gate charge (16 nC typical)
- High performance trench technology for extremely low R_{DS(ON)}
- High power and current handling capability





Absolute Maximum Ratings T_A=25°C unless otherwise noted

| Symbol | Parameter Drain-Source Voltage | | Ratings | Units V |
|-----------------------------------|---|------------|-------------|------------|
| V _{DSS} | | | 20 | |
| V _{GSS} | Gate-Source Voltage | | ± 12 | V |
| I_D | Drain Current - Continuous | (Note 1a) | 9.4 | А |
| | – Pulsed | | 38 | |
| P _D | Power Dissipation for Dual Operation | | 2 | W |
| | Power Dissipation for Single Operation | (Note 1a) | 1.6 | |
| | | (Note 1b) | 1 | |
| | | (Note 1c) | 0.9 | |
| T _J , T _{STG} | Operating and Storage Junction Temperat | ture Range | -55 to +150 | °C |

Thermal Characteristics

| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 78 | °C/W |
|-----------------|---|-----------|----|------|
| Reic | Thermal Resistance, Junction-to-Case | (Note 1) | 40 | °C/W |

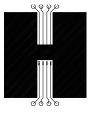
Package Marking and Ordering Information

| Device Marking | Device | Reel Size | Tape width | Quantity |
|----------------|----------|-----------|------------|------------|
| FDS6898A | FDS6898A | 13" | 12mm | 2500 units |

Electrical Characteristics T_A = 25°C unless otherwise noted **Symbol** Min Max **Units Parameter Test Conditions** Typ **Off Characteristics** $\mathsf{BV}_{\mathsf{DSS}}$ Drain-Source Breakdown Voltage $I_D = 250 \, \mu A$ V $V_{GS} = 0 V$, 20 $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ mV/°C Breakdown Voltage Temperature 21 <u>∆BV_{DSS}</u> Coefficient ΔT_{\perp} I_{DSS} Zero Gate Voltage Drain Current $V_{DS} = 16 \text{ V}, \quad V_{GS} = 0 \text{ V}$ 1 μĀ $V_{GS} = 12 \text{ V},$ nΑ I_{GSSF} Gate-Body Leakage, Forward $V_{DS} = 0 V$ 100 nΑ Gate-Body Leakage, Reverse $V_{GS} = -12 \text{ V}, V_{DS} = 0 \text{ V}$ -100 I_{GSSR} On Characteristics (Note 2) $V_{\text{GS(th)}}$ Gate Threshold Voltage $V_{DS} = V_{GS}$ $I_D = 250 \, \mu A$ 0.5 1 1.5 V Gate Threshold Voltage $I_D = 250 \mu A$, Referenced to $25^{\circ}C$ -3.5 $\Delta V_{GS(th)}$ mV/°C **Temperature Coefficient** ΔT_J R_{DS(on)} Static Drain-Source $V_{GS} = 4.5 \text{ V}, I_D = 9.4 \text{ A}$ 10 14 $\mathsf{m}\Omega$ On-Resistance $V_{GS} = 2.5 \text{ V}, I_D = 8.3 \text{ A}$ 13 18 14 21 $V_{GS} = 4.5 \text{ V}, I_D = 9.4 \text{ A}, T_J = 125^{\circ}\text{C}$ On-State Drain Current $V_{GS} = 4.5V$, $V_{DS} = 5 V$ 19 Α $I_{D(on)}$ $I_D = 9.4 A$ $V_{DS} = 5 V$ 47 S Forward Transconductance g_{FS} **Dynamic Characteristics** Input Capacitance 1821 C_{iss} $V_{DS} = 10 \text{ V},$ $V_{GS} = 0 V$, pF f = 1.0 MHz $C_{\text{oss}} \\$ **Output Capacitance** 440 pF C_{rss} Reverse Transfer Capacitance 208 pF Switching Characteristics (Note 2) Turn-On Delay Time $V_{DD} = 10 \text{ V},$ $I_D = 1 A$ 10 20 ns $t_{d(on)}$ Turn-On Rise Time $V_{GS} = 4.5 \text{ V}, \quad R_{GEN} = 6 \Omega$ t_r 15 27 ns Turn-Off Delay Time 34 55 $t_{d(off)}$ ns Turn-Off Fall Time 29 $t_{\rm f}$ 16 ns Q_q **Total Gate Charge** nC $V_{DS} = 10 \text{ V},$ $I_D = 9.4 A$ 16 23 Q_{qs} Gate-Source Charge $V_{GS} = 4.5 \text{ V}$ nC 3 $Q_{g\underline{d}}$ Gate-Drain Charge 4 nC **Drain-Source Diode Characteristics and Maximum Ratings** Maximum Continuous Drain-Source Diode Forward Current 1.3 Α I_S $V_{GS} = 0 \text{ V}, \quad I_{S} = 1.3 \text{ A}$ V_{SD} Drain-Source Diode Forward 0.7 1.2 V

Notes:

 R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8JC} is guaranteed by design while R_{8CA} is determined by the user's board design.



a) 78°C/W when mounted on a 0.5in² pad of 2 oz copper



b) 125°C/W when mounted on a 0.02 in² pad of 2 oz copper



 c) 135°C/W when mounted on a minimum mounting pad.

Scale 1:1 on letter size paper

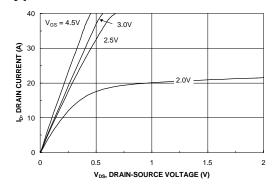
2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Voltage

3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied

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Typical Characteristics



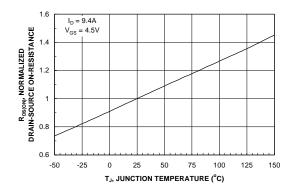
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Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



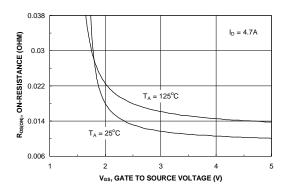
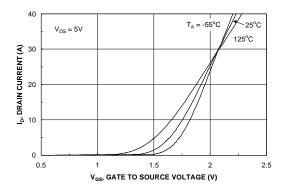


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



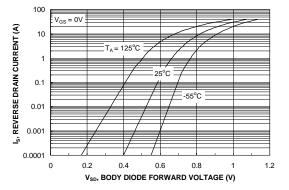
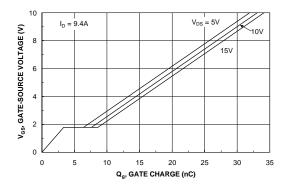


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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Typical Characteristics



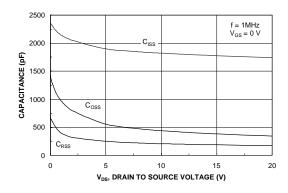
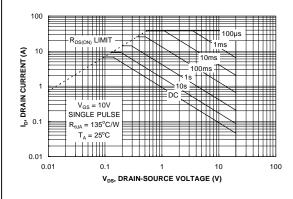


Figure 7. Gate Charge Characteristics.





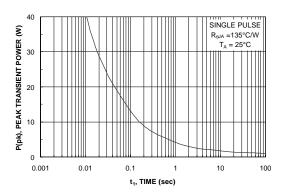


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

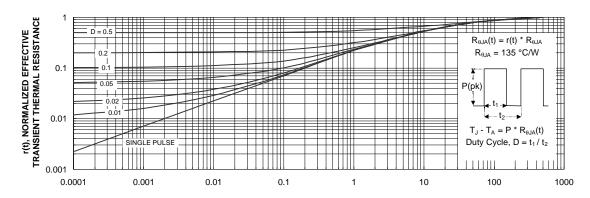


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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